

PATENT
81839.0107

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

Iida, et al.

Serial No: 10/009,910

Filed: December 12, 2001

For: Silicon Wafer, Silicon Epitaxial Wafer
and Annealed Wafer, and Method for
Producing the Same

Art Unit: 1722

Examiner: Song, M.J.

I hereby certify that this correspondence
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TRANSMITTAL OF INFORMATION
DISCLOSURE STATEMENT

Commissioner for Patents
Washington, D.C. 20231

Dear Sirs:

- The information disclosure statement submitted herewith is being filed within three months of the filing date of the application other than a continued prosecution application, or within three months of the date of entry into the national stage of an international application, or before the mailing date of a first Office Action on the merits, or before the mailing of a first Office action after the filing of a request for continued examination under §1.114, whichever event occurs last. 37 C.F.R. §1.97(b).
 - The information disclosure statement transmitted herewith is being filed *after* the period specified in §1.97(b), but *before* the mailing date of a final action under §1.113, or a notice of allowance under §1.311, or an action that otherwise closes prosecution in the application, whichever occurs first. A statement specified in §1.97(e) or a fee set forth in §1.17(p) is included. 37 C.F.R. §1.97(c).

§1.97(e) STATEMENT

I, the person signing below, state:

- that each item of information contained in the information disclosure statement was first cited in the attached communication from a foreign patent office in a counterpart foreign application and that the communication is dated not more than three months prior to the filing of the statement. 37 C.F.R. §1.97(e)(1).

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OR

- that no item of information contained in the information disclosure statement was cited in a communication from a foreign patent office in a counterpart foreign application, and, to the knowledge of the person signing the certification after making reasonable inquiry, no item of information contained in the information disclosure statement was known to any individual designated in

§1.56(c) more than three months prior to the filing of the statement. 37 C.F.R.
§1.97(e)(2).

OR FEE

- Attached is a fee set forth in 37 C.F.R. §1.17(p) for submission of an information disclosure statement under §1.97(c). (\$180.00). [OR:] Please charge the fee set forth in 37 C.F.R. §1.17(p) for submission of an information disclosure statement under §1.97(c) (\$180.00) to Deposit Account No. 50-1314. A copy of this petition is enclosed.

3. The information disclosure statement transmitted herewith is being filed *after* the period specified in §1.97(c), but before, or simultaneously with the payment of the issue fee. A statement specified in §1.97(e) and a fee set forth in §1.17(p) are included. 37 C.F.R. §1.97(d).

§1.97(e) STATEMENT

I, the person signing below, state:

- that each item of information contained in the information disclosure statement was first cited in the attached communication from a foreign patent office in a counterpart foreign application and that the communication is dated not more than three months prior to the filing of the statement. 37 C.F.R. §1.97(e)(1).

OR

- that no item of information contained in the information disclosure statement was cited in a communication from a foreign patent office in a counterpart foreign application, and, to the knowledge of the person signing the certification after making reasonable inquiry, no item of information contained in the information disclosure statement was known to any individual designated in §1.56(c) more than three months prior to the filing of the statement. 37 C.F.R. §1.97(e)(2).

AND FEE

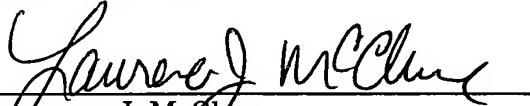
- Attached is a fee set forth in 37 C.F.R. §1.17(p) for submission of an information disclosure statement under §1.97(d). (\$180.00).
4. If it should be determined that for any reason either an insufficient fee or an excessive has been paid, please charge any insufficiency or credit any overpayment necessary to ensure consideration of the information disclosure statement for the above-identified application to Deposit Account No. 50-1314. A copy of this petition is enclosed.
5. A list of 2 reference(s) is in the enclosed Form PTO-1449.

NON-ENGLISH LANGUAGE REFERENCES

- Enclosed is a Japanese language office action for a counterpart application.
- The applicant has provided a translation of one of the cited references as a matter of courtesy. The translation has not been reviewed for accuracy.
- Set forth below are comments provided by the applicant's home country counsel on the relevancy of non-English language references:

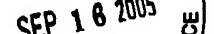
Respectfully submitted,
HOGAN & HARTSON L.L.P.

By:


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Date: September 13, 2005

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<p>FORM PTO-1449</p> <p>INFORMATION DISCLOSURE CITATION IN AN APPLICATION</p> <p>(Use several sheets if necessary)</p>		<p>Docket Number (Optional) 81839.0107</p> <p>Application Number 10/009,910</p> <p>Applicant IIDA, et al.</p> <p>Filing Date December 12, 2001</p> <p>Group Art Unit 1722</p>
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U.S. PATENT DOCUMENTS

FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						YES	NO
	2001-274166	10/05/01	JAPAN			Abstract	

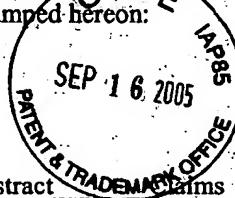
OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

"MOS Device Epitaxial Wafer", edited by Hirota Sumitomo, Realize Limited 6/30/98, pgs. 13-15

EXAMINER	DATE CONSIDERED
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S.N. 10/009,910 File No. 81639.017 Date Mailed 9/13/05 By: LJM/SF
Title Silicon Wafer, Silicon Epitaxial Wafer
(Client Name) Shin-Etsu

The Following due _____ in the U.S. Patent and Trademark office was received in the Patent & Trademark Office on the date stamped hereon:



- Amendment
 Preliminary Amendment
 PCT Application Including
 Pages Spec. _____ Page Abstract Claims
 Application for Patent Including
 Pages Spec. _____ Page Abstract Claims
 Declaration, Affidavit of Oath (_____ Page(s))
 Assign. Ck. No. _____ for \$ _____
 Verified Statement
 Letter of Transmittal of IDS
Amendment Under 37 C.F.R. 1.312(a)
 Check No. DA for \$ 160.50
 Check No. _____ for \$ _____
 Check No. _____ for \$ _____
- Drawing: # of Sheets _____
Formal _____ Informal
 Issue Fee Transmittal
 Letter Re _____
 Notice of Appeal
 Petition for _____
 Advance soft copy order
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 IDS: 2 References
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Publication Fee _____
Priority _____